PCN Number:		20131220000							PCN Date: 01/06/2014				
Title:	Title: Design Change for device CAB4AZNRR (DDR4 Register/PLL Buffer)												
Custom	er Contact:	PCN	PCN Manager Phone			:	+1(214)480-6037				Quality Services		
Proposed 1 st Ship Da		te: 04/06/2014			014		Estimated			•	Date provided at		
Change	Type:					Ava			ilability:	sample request			
Change Type: Assembly Site			Assembly Proc				s	Γ	7	Assembly Materials			
Design			Electrical Specific					Ī			Mechanical Specification		
Test Site			Packing/Shipping							Test Proc			
	Wafer Bump Site				Bump Ma					Wafer Bump Process			
Waf	er Fab Site				Fab Mate					Wafer Fab Process			
				Part nu	umber ch								
D					PCN	L	<u>Details</u>						
Descrip	tion of Chang	je:											
This notification is to inform of a design revision for device CAB4AZNRR (DDR4 Register/PLL Buffer). This design change does not affect the device's guaranteed datasheet specifications or electrical performance. The table below describes changes that were made:													
	Output Drive		ta	nco (Pon) offcot		Benefit of Cha				ngo		
Disable Output Drive r							Calibrate to center of spec range.						
Modify Input Bus Termination structure. Reduce leakage.													
Reason for Change:													
Output resistance (Ron) and input leakage partially too high													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Changes to product identification resulting from this PCN:													
None													
Product Affected:													
CAB4AZNRR													
Changes to product identification resulting from this PCN:													
 Date code will be used to identify new material. All products assembled from Nov 2013 and later will be new material. 													

Qualification Data: Approved 12/17/2013								
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle: CAB4AZNRR								
Package/Die Construction Details								
Assembly Site: Amkor K4			# Pins-Designator, Family:	253-	53-ZNR, FCBGA			
Fab Process:	C021	Die Revision: CAB			1A6 HVM			
Qualification: Plan Test Results								
Reliability Test		Cor	nditions	Sample Size (PASS/FAIL)				
ESD HBM		+/-	1500V, 2000V	3/0				
ESD CDM	·	+/-	500V	3/0				
Latch-up	_	(pe	r JESD78)	3/0				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com